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Electronic Version v1.1

Stylesheet Version v1.1.0

Title of Invention	METHOD FOR FORMING INTERCONNECTS ON THIN WAFERS
<p>Application Number :</p> <p>Date :</p> <p>First Named Applicant: Leonard J Gardecki</p> <p>Confirmation Number:</p> <p>Attorney Docket Number: BUR920030026US1</p>	
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<p>Submitted By:</p> <p>William D Sabo Registered Number: 27,465</p>	<p>Elec. Sign.</p> <p>William D. Sabo /s/ Attorney</p>

Documents being submitted:	Files
us-fee-sheet	BUR920030026-usfees.xml us-fee-sheet.xsl us-fee-sheet.dtd
us-ids	BUR920030026-usidst.xml us-ids.dtd us-ids.xsl
us-request	BUR920030026-usrequ.xml us-request.dtd us-request.xsl
us-assignment	BUR920030026-usassn.xml us-assignment.xsl us-assignment.dtd BUR920030026assignment1.tif BUR920030026assignment2.tif
us-declaration application-body	BUR920030026DEC1.tif BUR920030026-trans.xml us-application-body.xsl application-body.dtd wipo.ent mathml2.dtd mathml2-qname-1.mod isoamsa.ent isoamsb.ent isoamsc.ent isoamsn.ent isoamso.ent isoamsr.ent isogr3.ent isomfrk.ent isomopf.ent isomscr.ent isotech.ent isobox.ent isocyr1.ent isocyr2.ent isodia.ent isolat1.ent isolat2.ent isonum.ent isopub.ent mmlextra.ent mmlalias.ent soextblx.dtd BUR20030026drw1.tif BUR20030026drw2.tif BUR20030026drw3.tif BUR20030026drw4.tif BUR20030026drw5.tif BUR20030026drw6.tif

us-declaration	BUR20030026drw7.tif
us-declaration	BUR20030026drw8.tif
us-declaration	BUR20030026drw9.tif
	BUR20030026drw10.tif
	BUR20030026drw11.tif
	BUR20030026drw12.tif
	BUR920030026DEC2.tif
	BUR920030026DEC3.tif
	BUR920030026DEC4.tif
Comments	
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